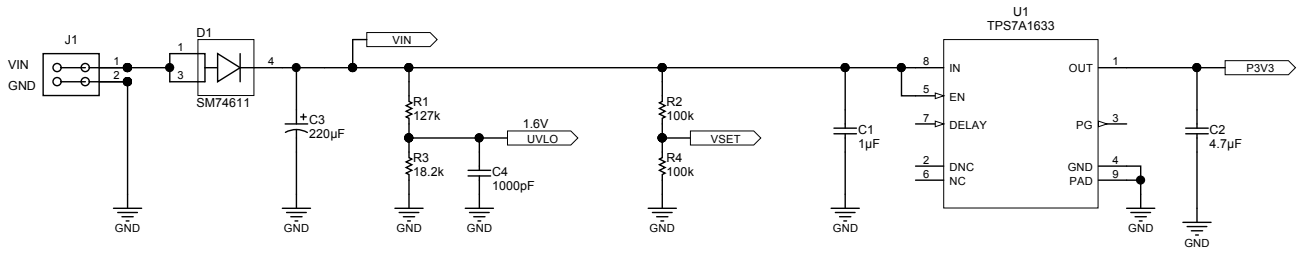
Revision History	
Revision	Notes
A	* Layout
B	* Built & Tested

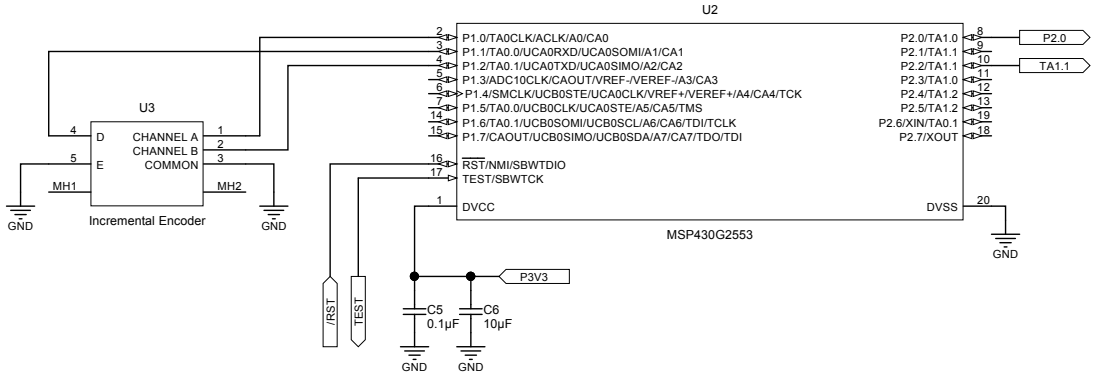
Input
10 .. 30V

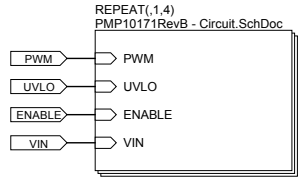


Undervoltage Lockout

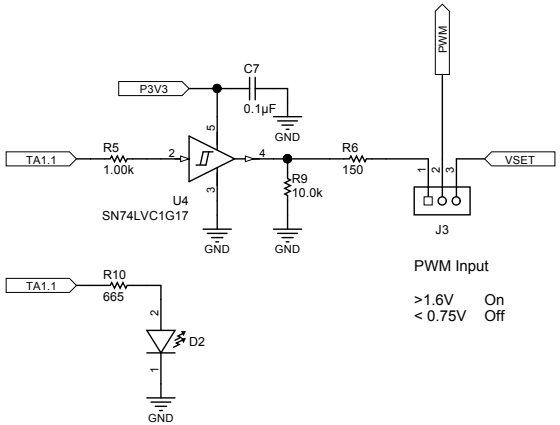
>9.8V On
< 9.35V Off

Auxiliary Voltage



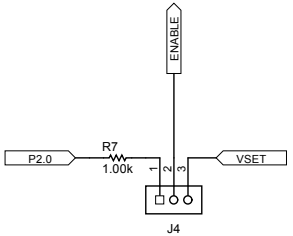


4-Channel LED Driver



PWM Input

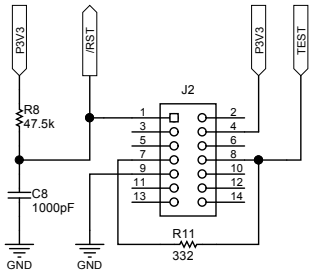
>1.6V On
< 0.75V Off



Enable

>1.6V On
< 0.75V Off

2-Wire JTAG Interface (Spy-Bi-Wire)



FID1 FID2 FID3 FID4
FID5 FID6 FID7 FID8

Number: PMP10171	Rev: B	Designed for: Public Release	Mod. Date: 5/15/2015
SVN Rev: Not in version control		Project Title: LED Driver	
Drawn By:		Sheet Title:	
Engineer: Matthias Ulmann		Assembly Variant: [No Variations]	Sheet: 1 of 2
		File: PMP10171RevB - Top Level.SchDoc	Size: A3
		Contact: http://www.ti.com/support	

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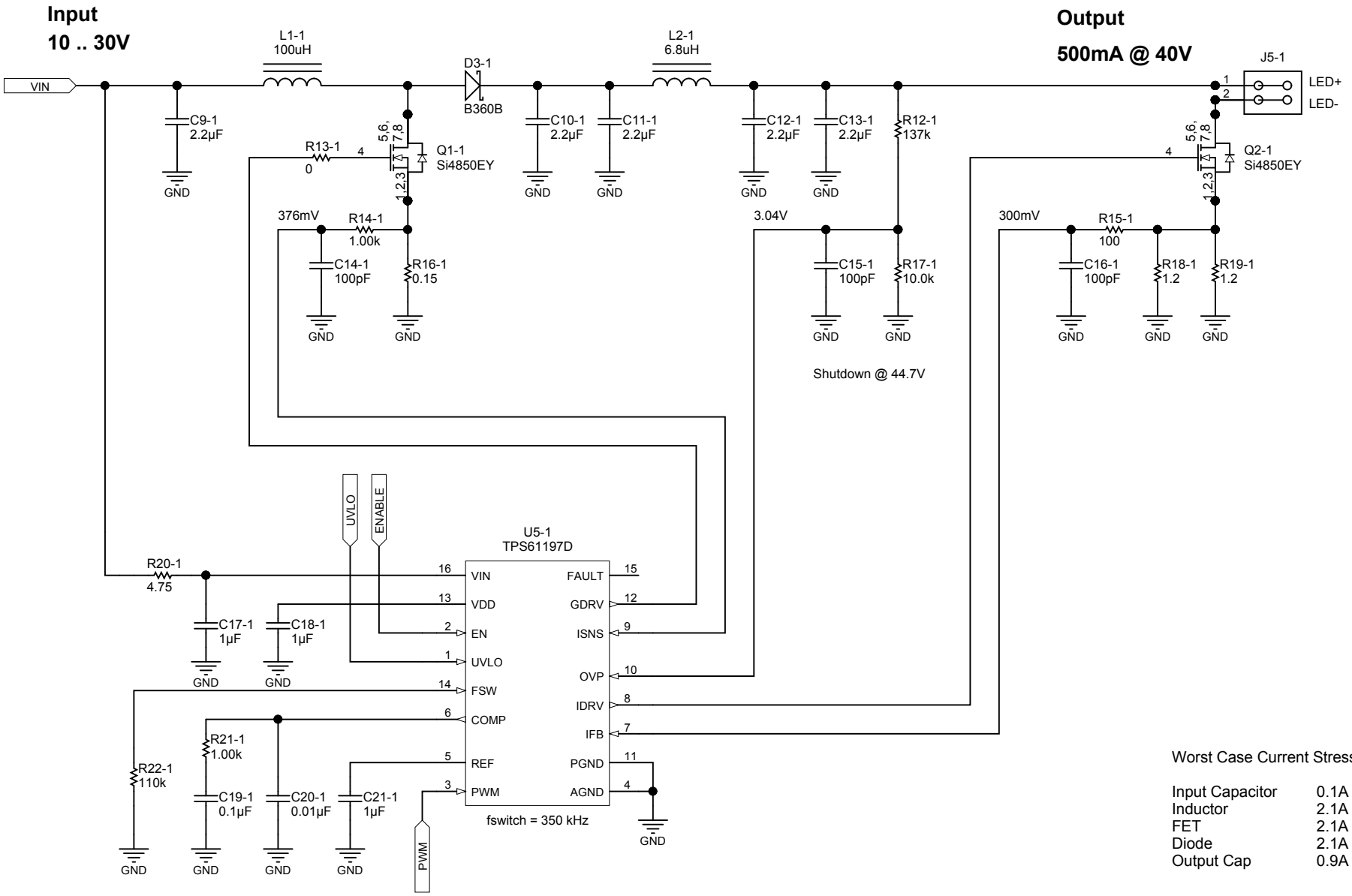
http://www.ti.com



Worst Case Current Stress

Input Capacitor	0.1A rms
Inductor	2.1A peak, 2.0A rms
FET	2.1A peak, 1.8A rms
Diode	2.1A peak, 0.5A avg
Output Cap	0.9A rms

Number: PMP10171	Rev: B	Designed for: Public Release	Mod. Date: 5/15/2015
SVN Rev: Not in version control		Project Title: LED Driver	
Drawn By:		Sheet Title:	
Engineer: Matthias Ulmann		Assembly Variant: [No Variations]	Sheet: 2 of 2
		File: PMP10171RevB - Circuit.SchDoc	Size: A4
		Contact: http://www.ti.com/support	

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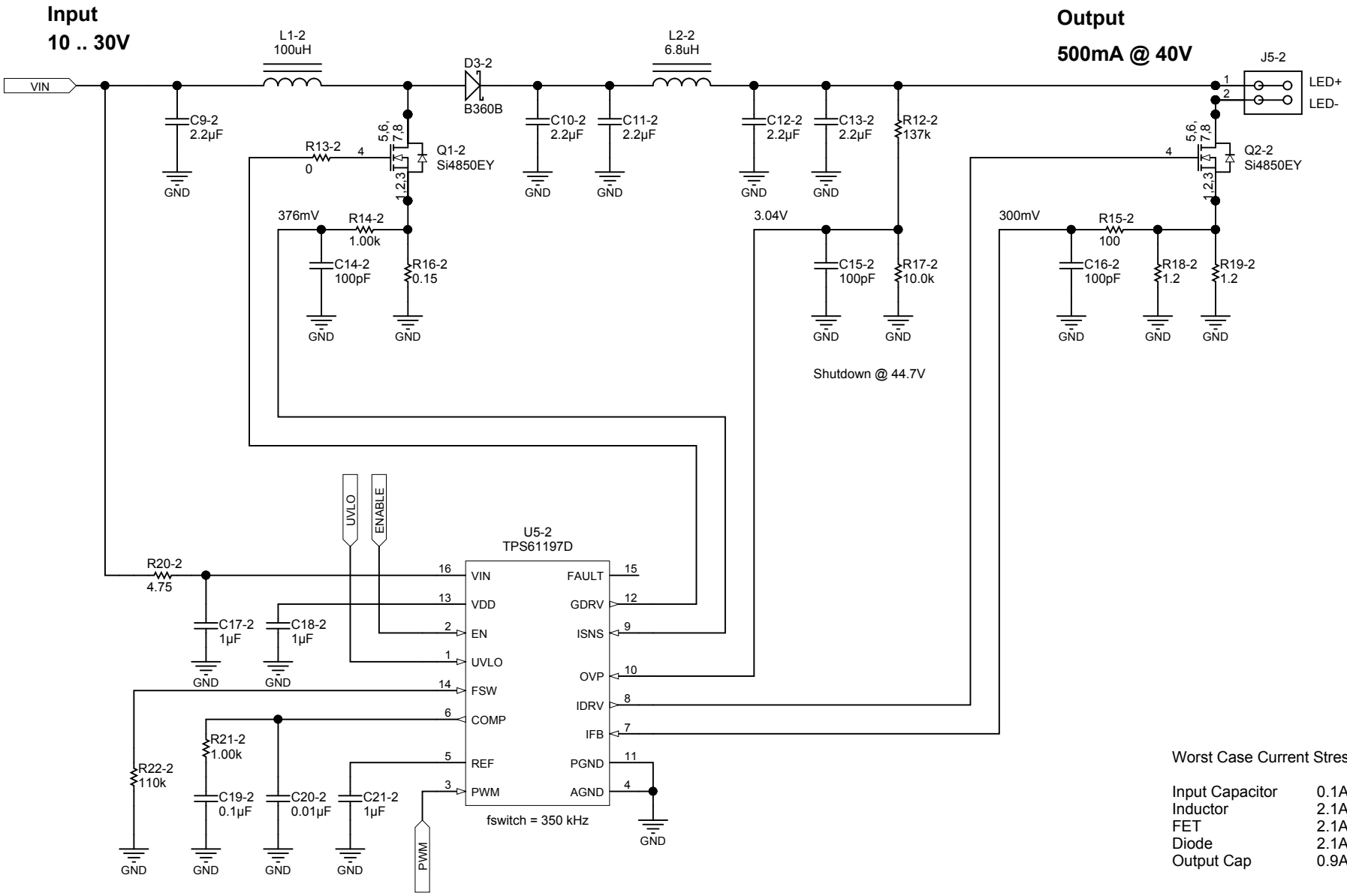

Worst Case Current Stress

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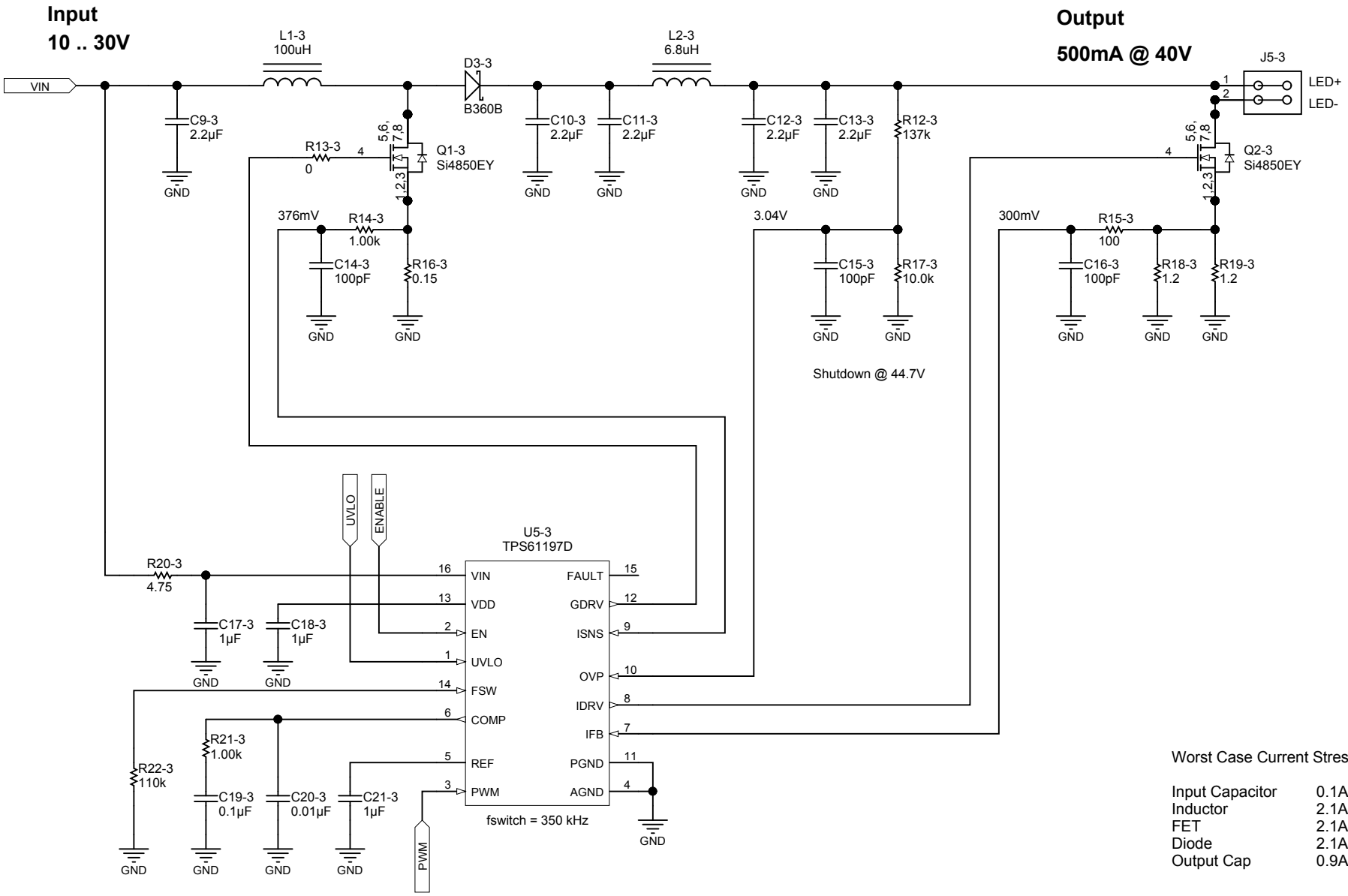

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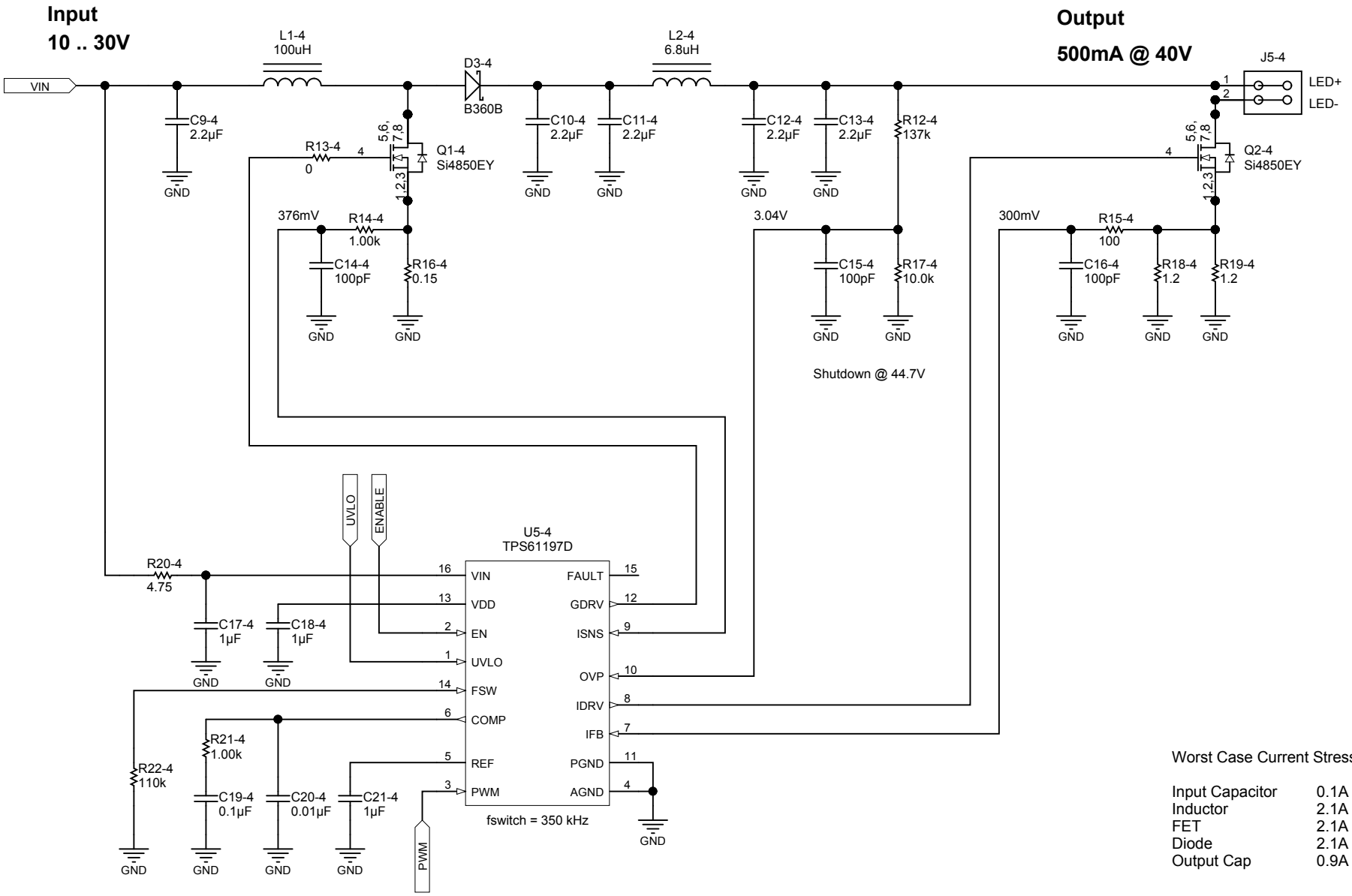

Number: PMP10171	Rev: B	Designed for: Public Release	Mod. Date: 5/15/2015
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